

Title (en)  
Lead-free, free-cutting copper alloys

Title (de)  
Bleifreie Automatenkupferlegierung

Title (fr)  
Alliage de cuivre de décolletage sans plomb

Publication  
**EP 1600515 A3 20051214 (EN)**

Application  
**EP 05017189 A 19981116**

Priority  
• EP 98953071 A 19981116  
• JP 28859098 A 19981012

Abstract (en)  
[origin: EP1559802A1] Lead-free copper alloys with industrially satisfactory machinability comprising 69 to 79 percent, by weight, of copper, 2.0 to 4.0 percent, by weight, of silicon, and the remaining percent, by weight, of zinc. <IMAGE>

IPC 1-7  
**C22C 9/04; C22F 1/08**

IPC 8 full level  
**C22F 1/00** (2006.01); **C22C 9/04** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP KR)  
**C22C 9/04** (2013.01 - EP KR); **C22F 1/08** (2013.01 - EP)

Citation (search report)  
• [A] US 2237774 A 19410408 - WOOD MAURICE L  
• [A] FR 1031211 A 19530622  
• [A] PATENT ABSTRACTS OF JAPAN vol. 1998, no. 04 31 March 1998 (1998-03-31)  
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